



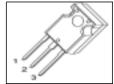
#### **Cool MOS™ Power Transistor**

#### **Feature**

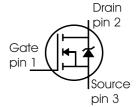
- New revolutionary high voltage technology
- Ultra low gate charge
- Periodic avalanche rated
- Extreme dv/dt rated
- High peak current capability
- Improved transconductance
- Pb-free lead plating; RoHS compliant
- Qualified according to JEDEC<sup>0)</sup> for target applications

V <sub>DS</sub> @ T <sub>imax</sub>	650	٧
R <sub>DS(on)</sub>	0.19	Ω
/ <sub>D</sub>	20.7	Α





Туре	Package	Ordering Code	Marking
SPW20N60C3	PG-TO247	Q67040-S4406	20N60C3



### **Maximum Ratings**

Parameter	Symbol	Value	Unit
Continuous drain current	$I_{D}$		А
$T_{\rm C}$ = 25 °C		20.7	
$T_{\rm C}$ = 100 °C		13.1	
Pulsed drain current, $t_p$ limited by $T_{jmax}$	I <sub>D puls</sub>	62.1	
Avalanche energy, single pulse	E <sub>AS</sub>	690	mJ
$I_{\rm D}$ = 10 A, $V_{\rm DD}$ = 50 V			
Avalanche energy, repetitive $t_{AR}$ limited by $T_{jmax}$ <sup>1</sup>	E <sub>AR</sub>	1	
$I_{\rm D}$ = 20 A, $V_{\rm DD}$ = 50 V			
Avalanche current, repetitive $t_{AR}$ limited by $T_{jmax}$	I <sub>AR</sub>	20	А
Reverse diode dv/dt <sup>4)</sup>	dv/dt	15	V/ns
Gate source voltage static	$V_{GS}$	±20	V
Gate source voltage AC (f >1Hz)	$V_{GS}$	±30	
Power dissipation, $T_{\rm C}$ = 25°C	P <sub>tot</sub>	208	W
Operating and storage temperature	$T_{\rm j}$ , $T_{\rm stg}$	-55 +150	°C





**Maximum Ratings** 

Parameter	Symbol	Value	Unit
Drain Source voltage slope	d <i>v</i> /d <i>t</i>	50	V/ns
$V_{\rm DS}$ = 480 V, $I_{\rm D}$ = 20.7 A, $T_{\rm j}$ = 125 °C			

### **Thermal Characteristics**

Parameter	Symbol		Values		
		min.	typ.	max.	
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	0.6	K/W
Thermal resistance, junction - ambient, leaded	$R_{thJA}$	-	-	62	
Soldering temperature, wavesoldering	$T_{sold}$	-	-	260	°C
1.6 mm (0.063 in.) from case for 10s					

# **Electrical Characteristics,** at $T_j$ =25°C unless otherwise specified

Parameter	Symbol	Conditions		Values		
			min.	typ.	max.	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =0.25mA	600	-	-	V
Drain-Source avalanche	V <sub>(BR)DS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =20A	-	700	-	
breakdown voltage	, ,					
Gate threshold voltage	V <sub>GS(th)</sub>	$I_{\rm D}$ =1000 $\mu{\rm A},\ V_{\rm GS}$ = $V_{\rm DS}$	2.1	3	3.9	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =600V, V <sub>GS</sub> =0V,				μA
		<i>T</i> <sub>j</sub> =25°C,	-	0.5	25	
		<i>T</i> <sub>j</sub> =150°C	-	-	250	
Gate-source leakage current	$I_{\rm GSS}$	V <sub>GS</sub> =30V, V <sub>DS</sub> =0V	ı	-	100	nA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =13.1A,				Ω
		<i>T</i> <sub>j</sub> =25°C	-	0.16	0.19	
		<i>T</i> <sub>j</sub> =150°C	-	0.43	-	
Gate input resistance	R <sub>G</sub>	f=1MHz, open Drain	-	0.54	-	



**Electrical Characteristics** , at  $T_j$  = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Values		Unit
			min.	typ.	max.	
Transconductance	<i>g</i> fs	$V_{DS} \ge 2*I_D*R_{DS(on)max},$ $I_D = 13.1A$	-	17.5	-	S
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V,	-	2400	-	pF
Output capacitance	Coss	f=1MHz	-	780	-	
Reverse transfer capacitance	C <sub>rss</sub>		-	50	-	
Effective output capacitance, <sup>2)</sup> energy related		V <sub>GS</sub> =0V, V <sub>DS</sub> =0V to 480V	-	83	-	pF
Effective output capacitance, <sup>3)</sup> time related	C <sub>o(tr)</sub>		-	160	-	
Turn-on delay time	t <sub>d(on)</sub>	$V_{\rm DD}$ =380V, $V_{\rm GS}$ =0/13V, $I_{\rm D}$ =20.7A, $R_{\rm G}$ =3.6 $\Omega$ , $T_{\rm j}$ =125	-	10	-	ns
Rise time	<i>t</i> <sub>r</sub>	V <sub>DD</sub> =380V, V <sub>GS</sub> =0/13V,	-	5	-	
Turn-off delay time	<i>t</i> d(off)	I <sub>D</sub> =20.7A, R <sub>G</sub> =3.6Ω	_	67	100	
Fall time	<i>t</i> <sub>f</sub>		-	4.5	12	

### **Gate Charge Characteristics**

Gate to source charge	Q <sub>gs</sub>	V <sub>DD</sub> =480V, I <sub>D</sub> =20.7A	-	11	-	nC
Gate to drain charge	$Q_{gd}$		-	33	-	
Gate charge total	$Q_g$	V <sub>DD</sub> =480V, I <sub>D</sub> =20.7A,	-	87	114	
		V <sub>GS</sub> =0 to 10V				
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> =480V, I <sub>D</sub> =20.7A	-	5.5	-	V

<sup>&</sup>lt;sup>0</sup>J-STD20 and JESD22

<sup>&</sup>lt;sup>1</sup>Repetitve avalanche causes additional power losses that can be calculated as  $P_{\text{AV}} = E_{\text{AR}} * f$ .

 $<sup>^2</sup>C_{\text{o(er)}}$  is a fixed capacitance that gives the same stored energy as  $C_{\text{oss}}$  while  $V_{\text{DS}}$  is rising from 0 to 80%  $V_{\text{DSS}}$ .

 $<sup>^3</sup>C_{\rm o(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{\rm oss}$  while  $V_{\rm DS}$  is rising from 0 to 80%  $V_{\rm DSS}$ .

 $<sup>^4</sup>$ I<sub>SD</sub><=I<sub>D</sub>, di/dt<=400A/us, V<sub>DClink</sub>=400V, V<sub>peak</sub><V<sub>BR, DSS</sub>, T<sub>j</sub><T<sub>j,max</sub>. Identical low-side and high-side switch.

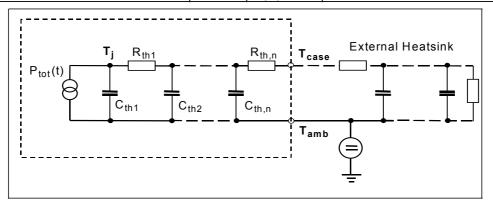


**Electrical Characteristics**, at  $T_i$  = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Values		
			min.	typ.	max.	
Inverse diode continuous	IS	<i>T</i> <sub>C</sub> =25°C	-	-	20.7	Α
forward current						
Inverse diode direct current,	/ <sub>SM</sub>		-	-	62.1	
pulsed						
Inverse diode forward voltage	$V_{\mathrm{SD}}$	$V_{GS}$ =0V, $I_F$ = $I_S$	-	1	1.2	V
Reverse recovery time	<i>t</i> <sub>rr</sub>	$V_{R}$ =480V, $I_{F}$ = $I_{S}$ ,	-	500	800	ns
Reverse recovery charge	Q <sub>rr</sub>	d <i>i<sub>F</sub></i> /d <i>t</i> =100Α/μs	-	11	-	μC
Peak reverse recovery current	I <sub>rrm</sub>		-	70	-	Α
Peak rate of fall of reverse	di <sub>rr</sub> /dt			1400	-	A/µs
recovery current						

**Typical Transient Thermal Characteristics** 

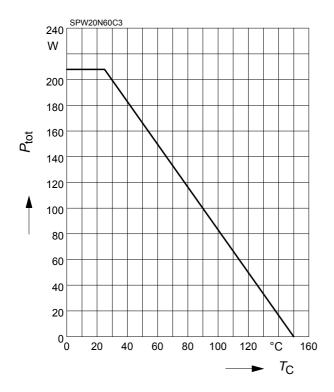
Symbol	Value	Unit	Symbol	Value	Unit
	typ.			typ.	
Thermal r	esistance		Thermal of	capacitance	
R <sub>th1</sub>	0.00769	K/W	C <sub>th1</sub>	0.0003763	Ws/K
R <sub>th2</sub>	0.015		C <sub>th2</sub>	0.001411	
R <sub>th3</sub>	0.029		C <sub>th3</sub>	0.001931	
R <sub>th4</sub>	0.114		C <sub>th4</sub>	0.005297	
R <sub>th5</sub>	0.136		C <sub>th5</sub>	0.012	
R <sub>th6</sub>	0.059		C <sub>th6</sub>	0.091	





### 1 Power dissipation

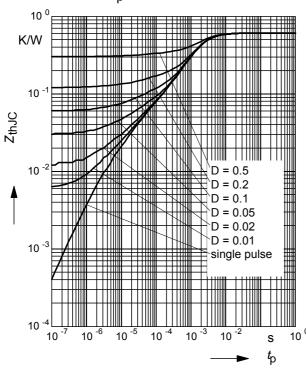
$$P_{\text{tot}} = f(T_{\text{C}})$$



### 3 Transient thermal impedance

$$Z_{\text{thJC}} = f(t_{\text{p}})$$

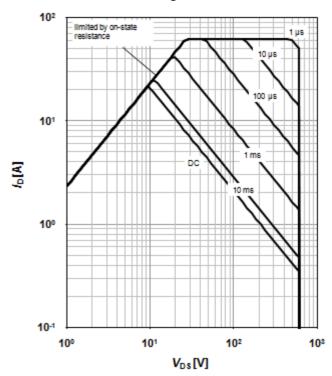
parameter:  $D = t_D/T$ 



## 2 Safe operating area

$$I_{\mathsf{D}} = f(V_{\mathsf{DS}})$$

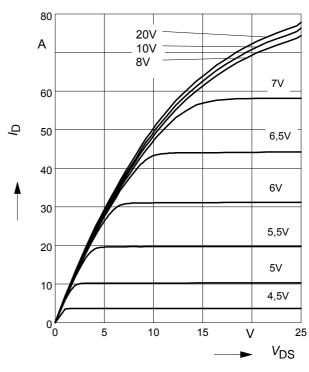
parameter : D = 0 ,  $T_C = 25$ °C



## 4 Typ. output characteristic

 $I_{D} = f(V_{DS}); T_{j}=25^{\circ}C$ 

parameter:  $t_p$  = 10  $\mu$ s,  $V_{GS}$ 

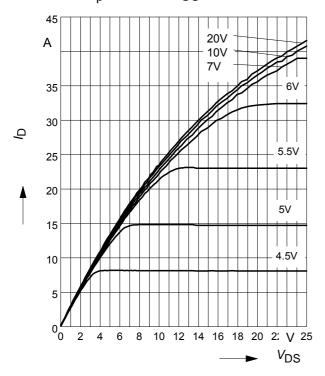


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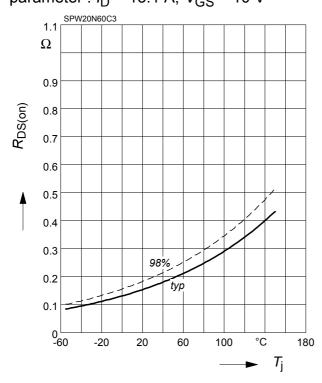
### 5 Typ. output characteristic

 $I_{\rm D} = f(V_{\rm DS}); T_{\rm j} = 150 ^{\circ} {\rm C}$ parameter:  $t_{\rm p} = 10 \ \mu {\rm s}, \ V_{\rm GS}$ 



### 7 Drain-source on-state resistance

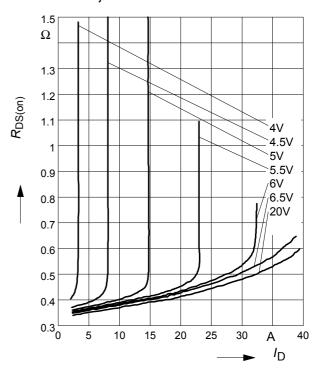
 $R_{\mathrm{DS(on)}} = f(T_{\mathrm{j}})$ parameter :  $I_{\mathrm{D}} = 13.1 \,\mathrm{A}, \, V_{\mathrm{GS}} = 10 \,\mathrm{V}$ 



### 6 Typ. drain-source on resistance

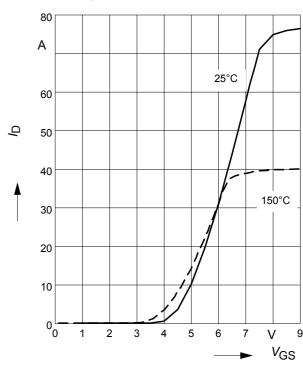
 $R_{\mathrm{DS(on)}} = f(I_{\mathrm{D}})$ 

parameter:  $T_j$ =150°C,  $V_{GS}$ 



### 8 Typ. transfer characteristics

 $I_{\rm D}$ = f (  $V_{\rm GS}$  );  $V_{\rm DS}$  $\geq$  2 x  $I_{\rm D}$  x  $R_{\rm DS(on)max}$  parameter:  $t_{\rm p}$  = 10  $\mu$ s



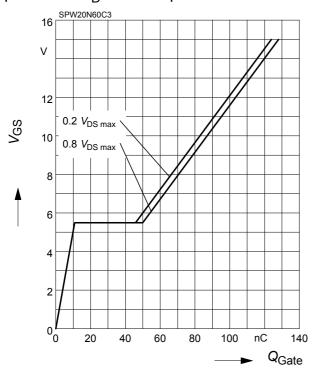
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#### 9 Typ. gate charge

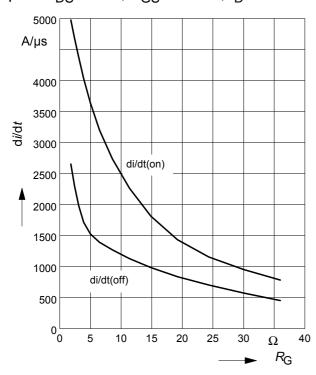
 $V_{GS} = f (Q_{Gate})$ 

parameter:  $I_D$  = 20.7 A pulsed



## 11 Typ. drain current slope

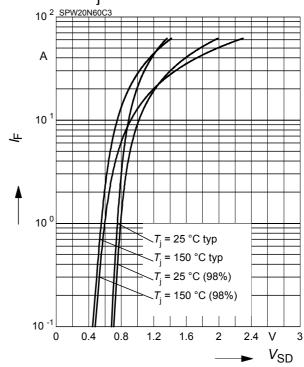
 $di/dt = f(R_G)$ , inductive load,  $T_j = 125$ °C par.:  $V_{DS} = 380$ V,  $V_{GS} = 0/+13$ V,  $I_D = 20.7$ A



### 10 Forward characteristics of body diode

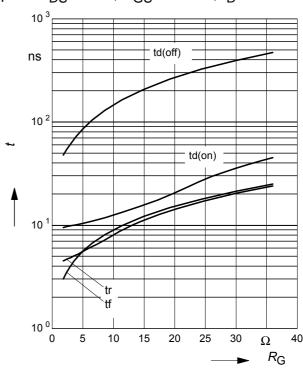
 $I_{\mathsf{F}} = f\left(\mathsf{V}_{\mathsf{SD}}\right)$ 

parameter:  $T_{j}$  ,  $t_{p}$  = 10  $\mu s$ 



## 12 Typ. switching time

 $t = f(R_{\rm G})$ , inductive load,  $T_{\rm j}$ =125°C par.:  $V_{\rm DS}$ =380V,  $V_{\rm GS}$ =0/+13V,  $I_{\rm D}$ =20.7 A

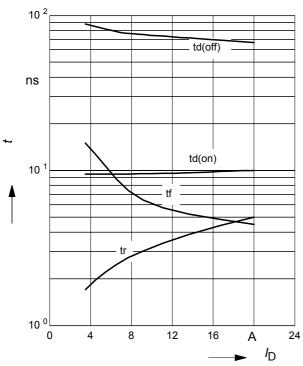


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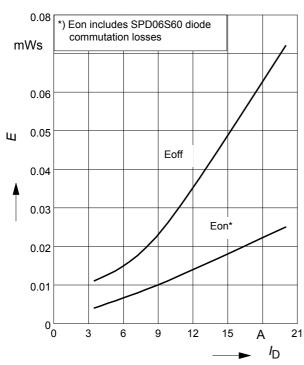
### 13 Typ. switching time

 $t = f(I_{\rm D})$ , inductive load,  $T_{\rm j}$ =125°C par.:  $V_{\rm DS}$ =380V,  $V_{\rm GS}$ =0/+13V,  $R_{\rm G}$ =3.6 $\Omega$ 



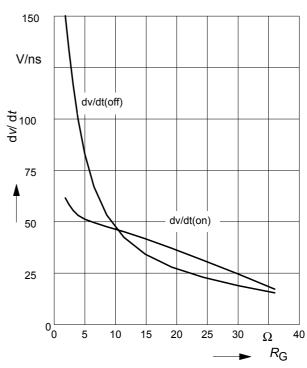
## 15 Typ. switching losses

 $E = f(I_D)$ , inductive load,  $T_j$ =125°C par.:  $V_{DS}$ =380V,  $V_{GS}$ =0/+13V,  $R_G$ =3.6 $\Omega$ 



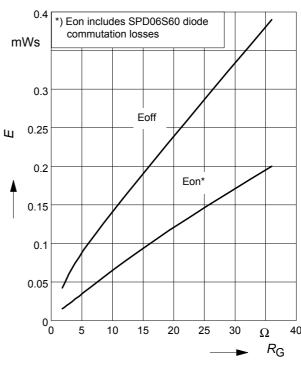
### 14 Typ. drain source voltage slope

 $dv/dt = f(R_G)$ , inductive load,  $T_j = 125$ °C par.:  $V_{DS}$ =380V,  $V_{GS}$ =0/+13V,  $I_D$ =20.7A



## 16 Typ. switching losses

 $E = f(R_{\rm G})$ , inductive load,  $T_{\rm j}$ =125°C par.:  $V_{\rm DS}$ =380V,  $V_{\rm GS}$ =0/+13V,  $I_{\rm D}$ =20.7A



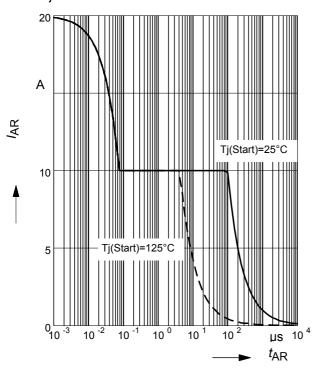
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#### 17 Avalanche SOA

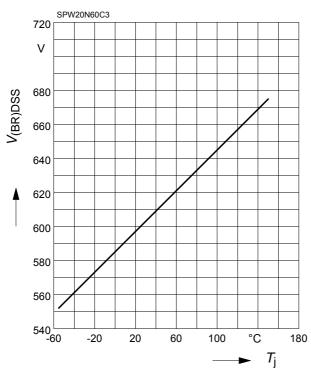
 $I_{AR} = f(t_{AR})$ 

par.:  $T_j \le 150 \,^{\circ}\text{C}$ 



## 19 Drain-source breakdown voltage

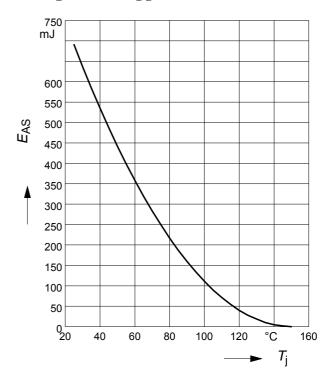
$$V_{(BR)DSS} = f(T_j)$$



### 18 Avalanche energy

 $E_{AS} = f(T_j)$ 

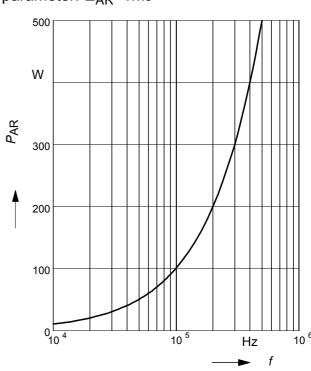
par.:  $I_D = 10 \text{ A}, V_{DD} = 50 \text{ V}$ 



### 20 Avalanche power losses

 $P_{\mathsf{AR}} = f(f)$ 

parameter: E<sub>AR</sub>=1mJ



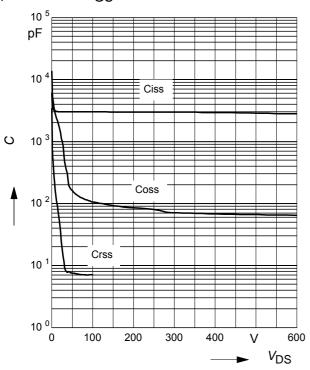




# 21 Typ. capacitances

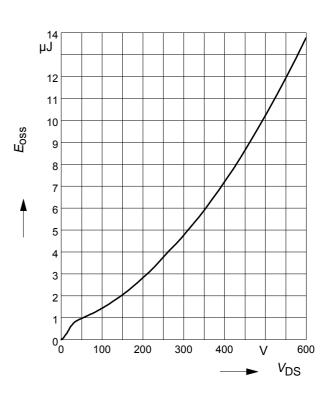
 $C = f(V_{DS})$ 

parameter:  $V_{GS}$ =0V, f=1 MHz

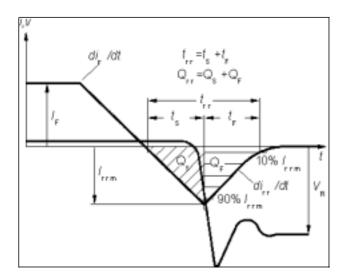


# 22 Typ. $C_{\rm OSS}$ stored energy

$$E_{\text{oss}} = f(V_{\text{DS}})$$

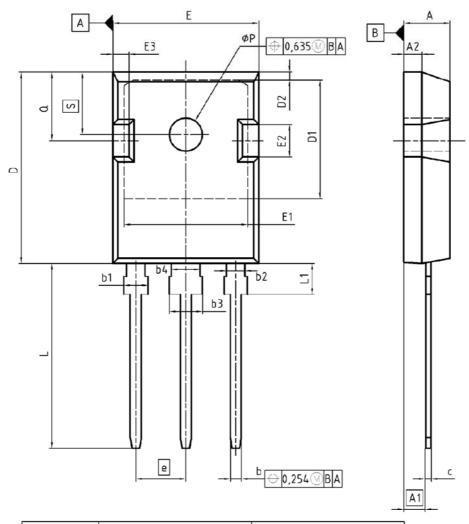


## Definition of diodes switching characteristics

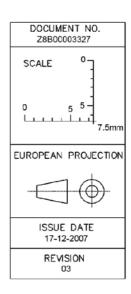




### PG-TO-247-3-1



DIM	MILLIM	ETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.16	0.193	0.203
A1	2.27	2.53	0.089	0.099
A2	1.85	2.11	0.073	0.083
Ь	1.07	1.33	0.042	0.052
b1	1.90	2.41	0.075	0.095
b2	1.90	2.16	0.075	0.085
b3	2.87	3.38	0.113	0.133
b4	2.87	3.13	0.113	0.123
С	0.55	0.68	0.022	0.027
D	20.82	21.10	0.820	0.831
D1	16.25	17.65	0.640	0.695
D2	1.05	1.35	0.041	0.053
E	15.70	16.03	0.618	0.631
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.68	2.60	0.066	0.102
е	5.	44	0.2	14
N	;	3	;	3
L	19.80	20.31	0.780	0.799
L1	4.17	4.47	0.164	0.176
øP	3.50	3.70	0.138	0.146
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248





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New package outlines TO-247

# 1 New package outlines TO-247

Assembly capacity extension for CoolMOSTM technology products assembled in lead-free package PG-TO247-3 at subcontractor ASE (Weihai) Inc., China (Changes are marked in blue.)

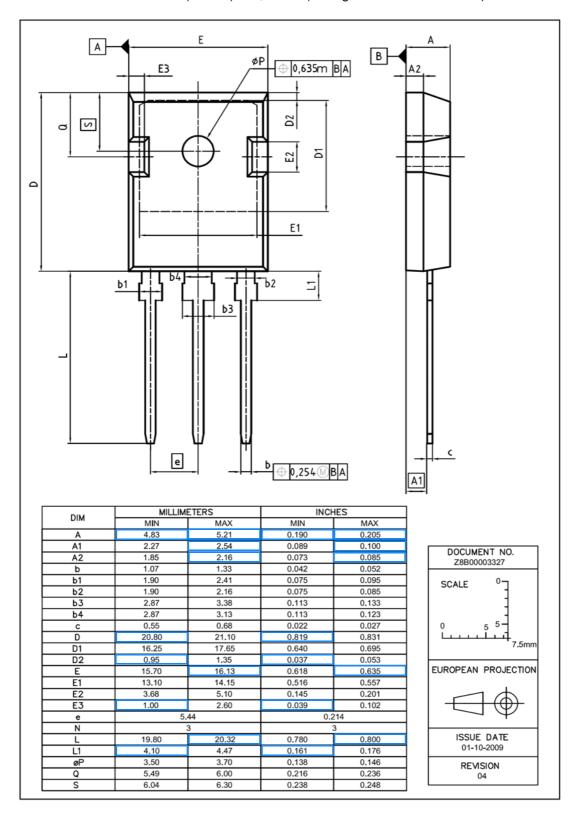


Figure 1 Outlines TO-247, dimensions in mm/inches

Final Data Sheet Erratum Rev. 2.0, 2010-02-01

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